



NSAI
Standards

Irish Standard
I.S. EN 62374-1:2010

Semiconductor devices -- Part 1: Time-dependent dielectric breakdown (TDDB) test for inter-metal layers (IEC 62374-1:2010 (EQV))

I.S. EN 62374-1:2010

Incorporating amendments/corrigenda issued since publication:
EN 62374-1:2010/AC:2011

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I.S. xxx: Irish Standard – national specification based on the consensus of an expert panel and subject to public consultation.

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Corrigendum to EN 62374-1:2010

The superseding information shall be deleted.

April 2011

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EUROPEAN STANDARD

EN 62374-1

NORME EUROPÉENNE

EUROPÄISCHE NORM

November 2010

ICS 31.080

Supersedes EN 62374:2007

English version

**Semiconductor devices -
Part 1: Time-dependent dielectric breakdown (TDDB) test for inter-metal
layers
(IEC 62374-1:2010)**

Dispositifs à semiconducteurs -
Partie 1: Essai de rupture diélectrique en
fonction du temps (TDDB) pour les
couches intermétalliques
(CEI 62374-1:2010)

Halbleiterbauelemente -
Teil 1: Prüfung auf zeitabhängigen
dielektrischen Durchbruch (TDDB) bei
Isolationsschichten zwischen metallischen
Leiterbahnen
(IEC 62374-1:2010)

This European Standard was approved by CENELEC on 2010-11-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47/2063/FDIS, future edition 1 of IEC 62374-1, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62374-1 on 2010-11-01.

This European Standard supersedes EN 62374:2007.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2011-08-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2013-11-01

Endorsement notice

The text of the International Standard IEC 62374-1:2010 was approved by CENELEC as a European Standard without any modification.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –

**Part 1: Time-dependent dielectric breakdown (TDDB)
test for inter-metal layers**

FOREWORD

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International Standard IEC 62374-1 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2063/FDIS	47/2077/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62374 series, under the general title *Semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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